

ABSTRACT OF THE DISCLOSURE

A heat radiator includes a water tank containing cooling liquid. A first radiating member has a top plate secured at top edges of the water tank. Multiple first fins are formed beneath the top plate and immersed in the cooling liquid. A heat insulating pad is adhered on the top plate. At least one semiconductor refrigerating component is mounted on the top plate and has a hot surface abutting the top plate and a cold surface exposed from the heat insulating pad. A second radiating member is positioned on the first radiating member and has a bottom plate with an area over the semiconductor refrigerating component. Multiple second fins are formed on the bottom plate. A fan is mounted on the second fins of the second radiating member.